Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- 1. (Withdrawn) A method of manufacturing a semiconductor device comprising:

 a first step of interposing an adhesive between a surface of a substrate on

 which an interconnect pattern is formed and a surface of a semiconductor chip on which

 electrodes are formed, said adhesive having conductive particles dispersed therein; and

 a second step in which pressure is applied between said semiconductor chip

 and said substrate, said interconnect pattern and said electrodes are electrically connected via

 at least part of said conductive particles of said adhesive, and said adhesive is caused to cover

 all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the
- 2. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1,

wherein said adhesive is provided in the first step at a thickness greater than the interval between said semiconductor chip and said substrate after the second step.

surface of the semiconductor chip on which the electrodes are formed.

- 3. (Canceled)
- 4. (Canceled)
- 5. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1,

wherein before the first step, said adhesive is previously disposed on the surface of said semiconductor chip on which said electrodes are formed.

6. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1, wherein before the first step, said adhesive is previously disposed on the surface of said substrate on which said interconnect pattern is formed.

- 7. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1, wherein said adhesive includes a shading material.
- 8. (Currently Amended) A semiconductor device, comprising:

 a semiconductor chip having electrodes;

 a substrate having an interconnect pattern; and

 an adhesive, said adhesive having a first portion and a second portion, said

 first portion interposed between a surface of said substrate on which said interconnect pattern

 is formed and a surface of said semiconductor chip on which said electrodes are formed, said

 second portion overlapping with said semiconductor chip; and said adhesive having

 conductive particles dispersed therein;

 conductive particles dispersed in said adhesive;

wherein said electrodes and said interconnect pattern are electrically connected via at least part of said conductive particles-of-said-adhesive; and

which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said second portion of said adhesive covers all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed, and a thickness of any part of said second portion of said adhesive is thicker than an interval between the surface of the semiconductor chip on which said electrodes are formed and said interconnect pattern on said substrate.

- 9. (Canceled)
- 10. (Canceled)
- 11. (Previously Presented) The semiconductor device as defined in claim 8, wherein said adhesive is provided to cover said interconnect pattern in its entirety.

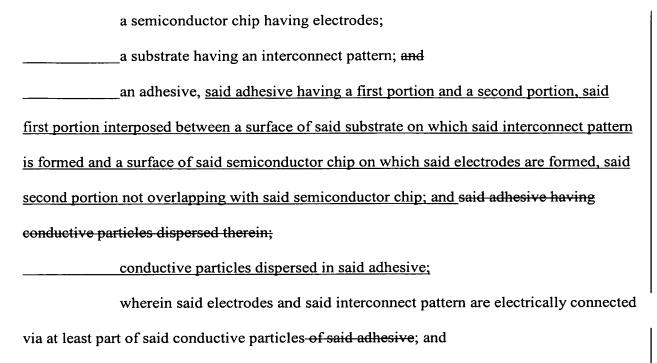
- 12. (Previously Presented) The semiconductor device as defined in claim 8, wherein said adhesive includes a shading material.
- 13. (Canceled)
- 14. (Currently Amended) A circuit board on which is mounted a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes;
a substrate having an interconnect pattern; and
an adhesive, said adhesive having a first portion and a second portion, said
first portion interposed between a surface of said substrate on which said interconnect pattern
is formed and a surface of said semiconductor chip on which said electrodes are formed, said
second portion not overlapping with said semiconductor chip; and said adhesive having
conductive particles dispersed therein;
conductive particles dispersed in said adhesive;

wherein said electrodes and said interconnect pattern are electrically connected via at least part of said conductive particles of said adhesive; and

which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said second portion of said adhesive covers all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed, and a thickness of any part of said second portion of said adhesive is thicker than an interval between the surface of the semiconductor chip on which said electrodes are formed and said interconnect pattern on said substrate.

15. (Currently Amended) An electronic instrument having a semiconductor device, the semiconductor device comprising:



which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said second portion of said adhesive covers all area of lateral surfaces of said semiconductor chip that is substantially perpendicular to the surface of the semiconductor chip on which the electrodes are formed, and a thickness of any part of said second portion of said adhesive is thicker than an interval between the surface of the semiconductor chip on which said electrodes are formed and said interconnect pattern on said substrate.

- 16. (Previously Presented) The semiconductor device as defined in claim 8, wherein at least a part of said adhesive has a thickness substantially the same as said semiconductor chip.
 - 17. (Canceled)
 - 18. (Canceled)
 - 19. (Canceled)
 - 20. (Canceled)

- 21. (Previously Presented) The circuit board as defined in claim 14, wherein a part of said adhesive covering all area of lateral surfaces of said semiconductor chip has a thickness substantially the same as said semiconductor chip.
- 22. (Previously Presented) The electronic instrument as defined in claim 15, wherein a part of said adhesive covering all area of lateral surfaces of said semiconductor chip has a thickness substantially the same as said semiconductor chip.
- 23. (Withdrawn) The method of manufacturing a semiconductor device as defined in claim 1,

wherein a part of said adhesive covering all area of said lateral surfaces of said semiconductor chip is formed to have part of said conductive particles dispersed therein.

- 24. (Currently Amended) The semiconductor device as defined in claim 8,

 wherein a part of said adhesive covering all area of said lateral surfaces of said

 semiconductor chip said second portion of said adhesive has part of said conductive particles dispersed therein.
- 25. (Currently Amended) The circuit board as defined in claim 14,
 wherein a part of said adhesive covering all area of said lateral surfaces of said
 semiconductor chip said second portion of said adhesive has part of said conductive particles
 dispersed therein.
- 26. (Currently Amended) The electronic instrument as defined in claim 15, wherein a part of said adhesive covering all area of said lateral surfaces of said semiconductor chip said second portion of said adhesive has part of said conductive particles dispersed therein.